

**In th Sp cification**

Amend the title as follows:

~~Methods for Conditioning Surfaces of Polishing Pads After Chemical Mechanical Polishing,~~  
and Apparatuses for Conditioning Surfaces of Polishing Pads

**RELATED PATENT DATA**

This patent resulted from a divisional application of U.S. Patent Application Serial  
No. 10/075,172, which was filed February 13, 2002.